Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

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**Top Material: Aluminum**

**Backside Material: Gold**

**Bond Pad Size: .004” Square**

**Backside Potential:**

**Mask Ref: MG-157**

**APPROVED BY: DK DIE SIZE .015x .015” DATE: 1/3/17**

**MFG: Motorola Semi THICKNESS .015” P/N: MBRC901**

**DG 10.1.2**

#### Rev B, 7/1